Form 1449\*

Atty. Docket No.: 303.434US2

Serial No. Unknown

# INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(Use several sheets if necessary)

Applicant: Pierre C. Fazan et al.

Filing Date: Herewith

Group: Unknown

#### U.S. PATENT DOCUMENTS

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Examiner Donghee Kary Date Considered

<sup>\*</sup>Substitute Disclosure Statement Form (PTO-1449)

<sup>\*\*</sup>EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Sheet 2 of 2

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Form 1449*	Atty. Docket No.: 303.434US2	Serial No. Unknown	
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#### FOREIGN PATENT DOCUMENTS

**Examiner						<u>Translation</u>
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